

## General Description

- 100% UIS Tested
- Advance SGT MOS Technology
- Low Gate Charge
- High Current Capability
- RoHS and Halogen-Free Compliant

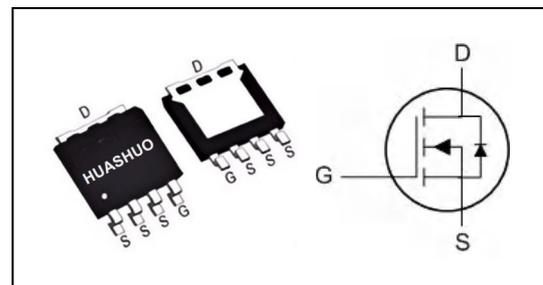
## Product Summary

$V_{DS}$	30	V
$R_{DS(ON),typ}$	0.35	m $\Omega$
$I_D$	390	A

## Application

- Power Management in Desktop Computer
- DC/DC Converters

## LFPAK5X6 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	390	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	245	A
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	53	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	41	A
$I_D@T_A=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	33	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	700	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	129	mJ
$I_{AS}$	Avalanche Current	50	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	140	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	2.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.9	$^\circ\text{C}/\text{W}$



**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	---	0.35	0.6	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A	---	0.6	0.9	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.7	2.2	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	2.5	---	Ω
Q <sub>g</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A	---	155	---	nC
Q <sub>g</sub>	Total Gate Charge (4.5V)		---	80	---	
Q <sub>gs</sub>	Gate-Source Charge		---	26	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	30	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω, I <sub>D</sub> =30A	---	16	---	ns
T <sub>r</sub>	Rise Time		---	59	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	135	---	
T <sub>f</sub>	Fall Time		---	114	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	8987	---	pF
C <sub>oss</sub>	Output Capacitance		---	3930	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	728	---	

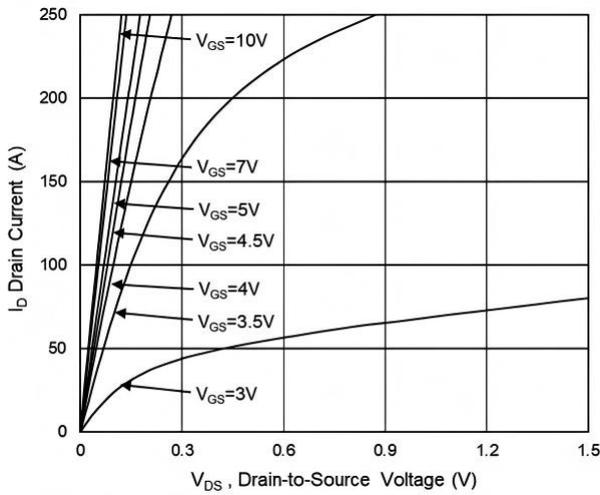
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =30A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	104	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	183	---	nC

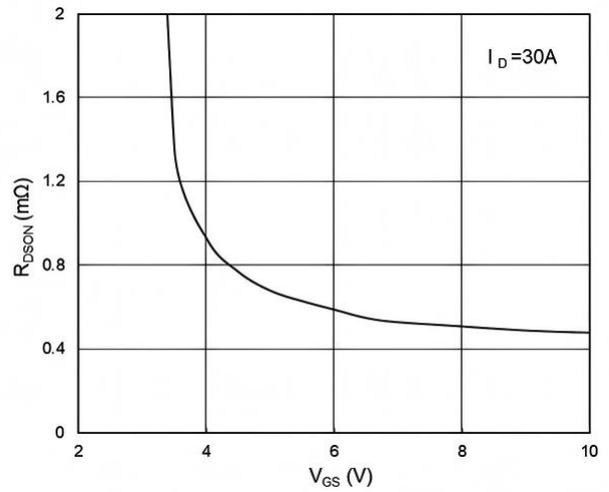
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=50A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 100A.

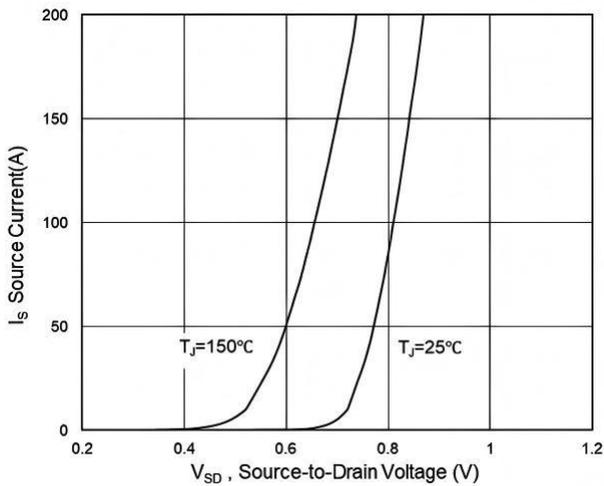
**Typical Characteristics**



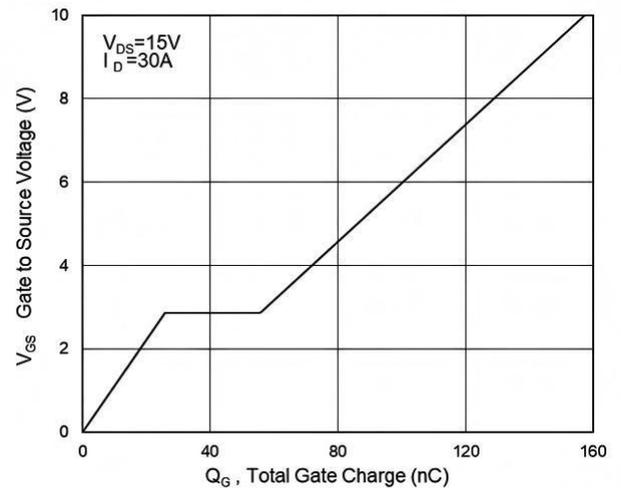
**Fig.1 Typical Output Characteristics**



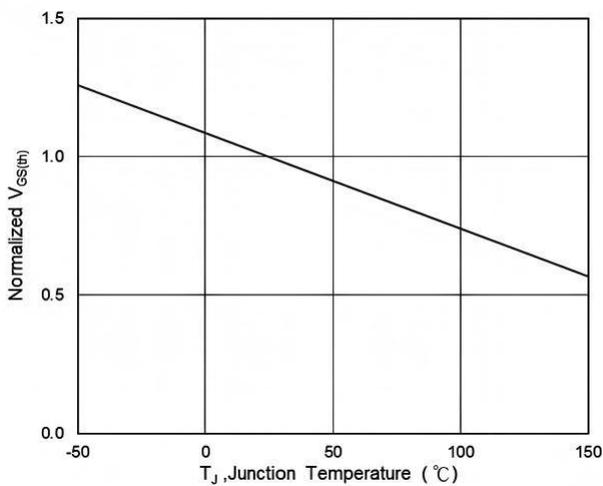
**Fig.2 On-Resistance vs G-S Voltage**



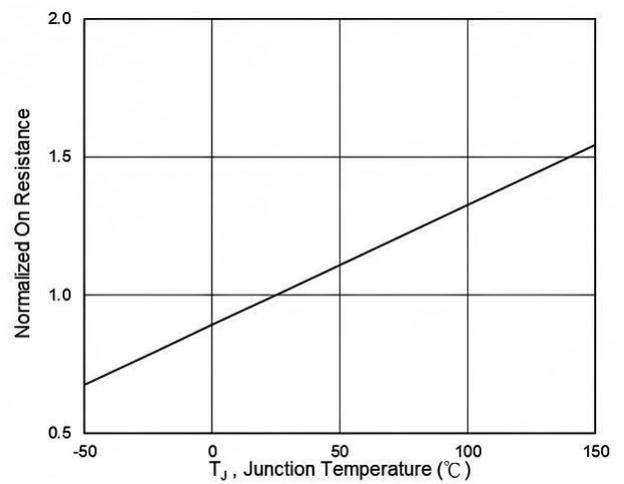
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



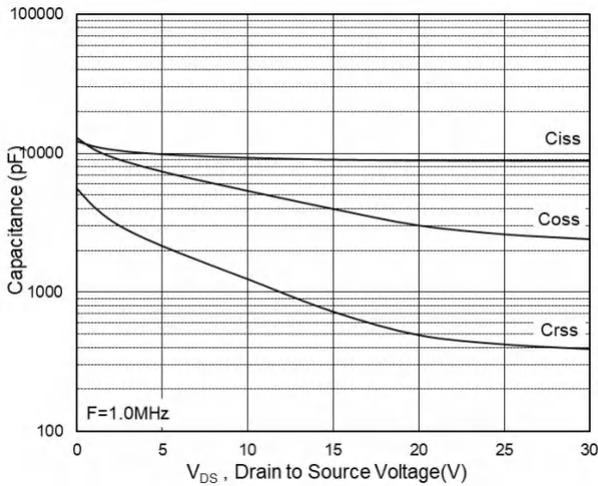
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



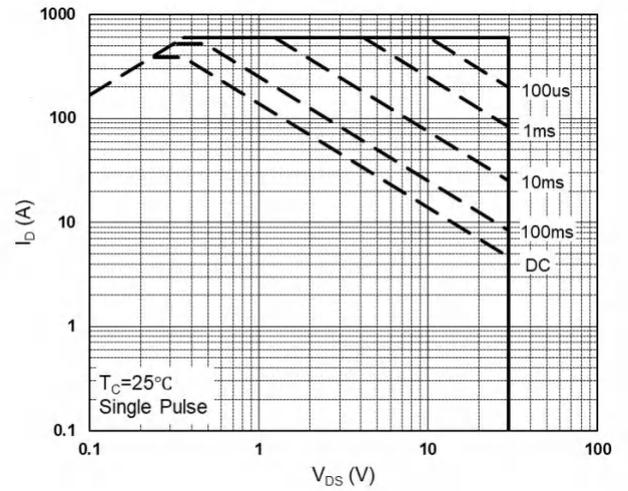
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



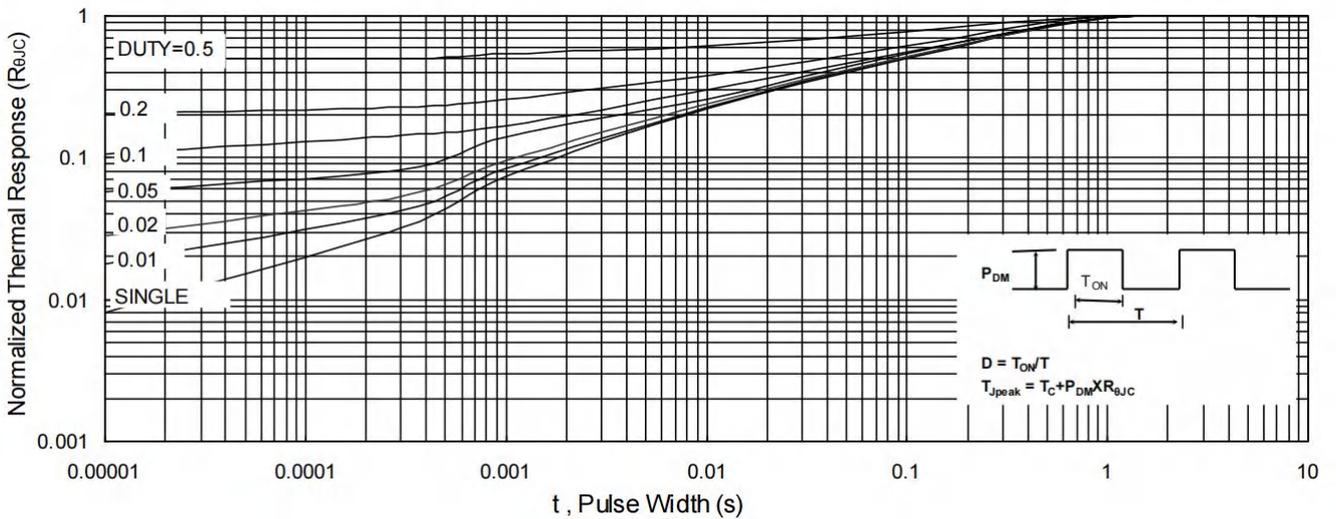
**N-Ch 30V Fast Switching MOSFETs**



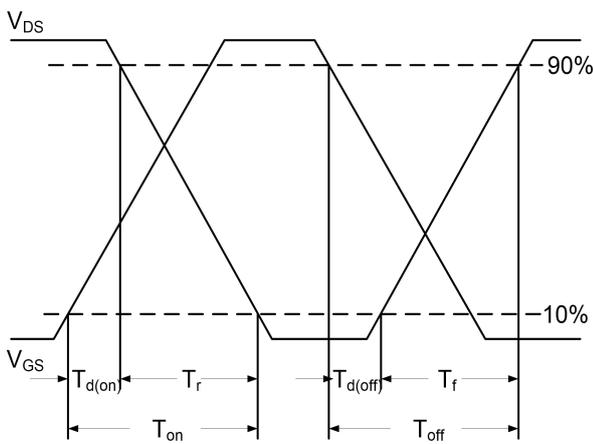
**Fig.7 Capacitance**



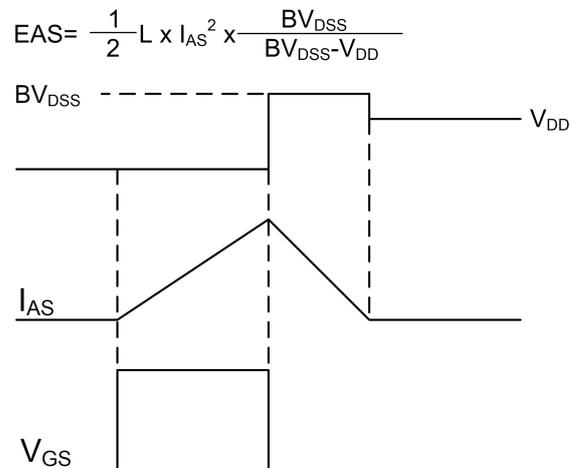
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**

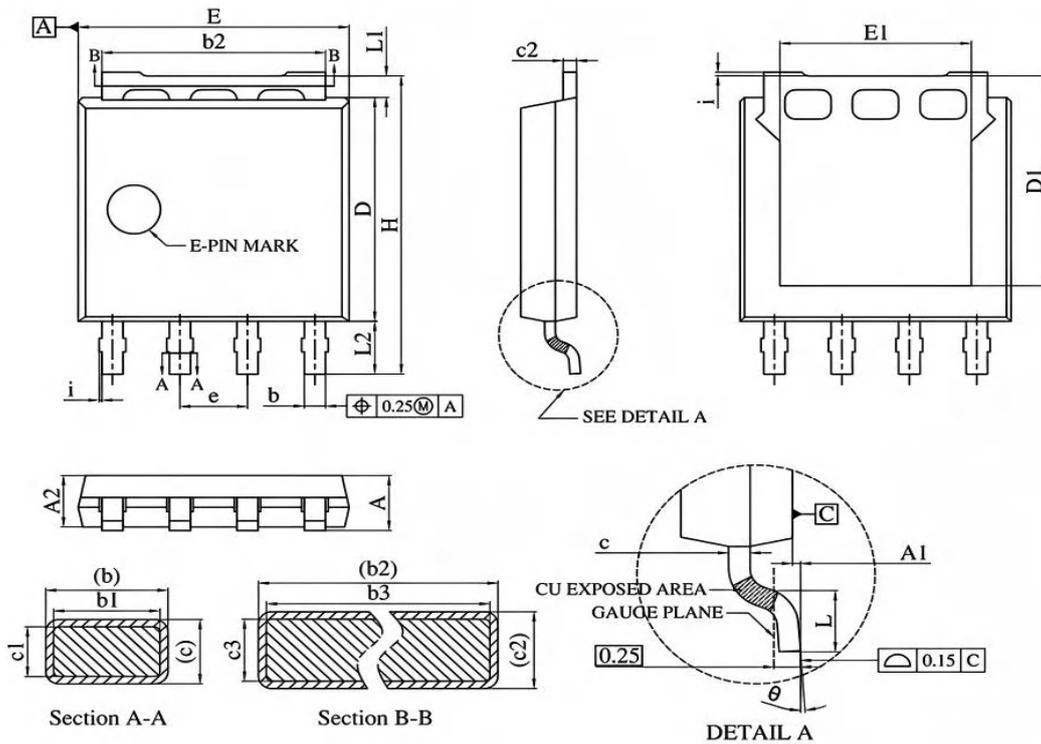


**Fig.11 Unclamped Inductive Switching Waveform**

## Ordering Information

<b>Part Number</b>	<b>Package code</b>	<b>Packaging</b>
<b>HSMA3078</b>	<b>LFPAK5*6</b>	<b>2000/Tape&amp;Reel</b>

### LFPAK5\*6 Package Outline



COMMON DIMENSIONS(MM)			
SYMBOLS	MIN	NOM	MAX
A	1.00	-	1.20
A1	0	-	0.15
A2	0.98	1.05	1.12
b	0.35	0.40	0.50
b1	0.32	0.43	0.54
b2	4.02	4.21	4.40
b3	4.00	4.19	4.37
c	0.18	0.20	0.25
c1	0.17	0.20	0.23
c2	0.23	0.25	0.30
c3	0.22	0.25	0.28
D	4.45	-	4.70
D1	4.20	-	4.45
E	4.95	-	5.40
E1	3.50	-	3.70
e	1.27 BSC.		
H	5.95	-	6.25
i	-	-	0.25
L	0.40	-	0.85
L1	0.270	-	0.57
L2	0.80	-	1.30
$\theta$	0°	-	8°

## HSMA3078 Marking:

